

ACF SCREEN™

MADE EXCLUSIVELY WITH  **CIRCUIT FOIL**

ACF-Screen™ is comprised of a Protective Poly release film adhered to a sheet of copper foil. It provides protection of the copper surface throughout the entire cycle of PCB lamination. ACF-Screen utilizes an inert adhesive which results in a residue-free copper surface during processing. The release film will uncouple during the lamination cycle, allowing for easy removal during break-down.

Benefits

Improve Your Yields

- Protect the copper surface
- Eliminate Epoxy Spots
- Reduce Pits and Dents due to airborne particulate
- Buffers the Copper Foil from damaged Separator Plates

Improve Your Productivity

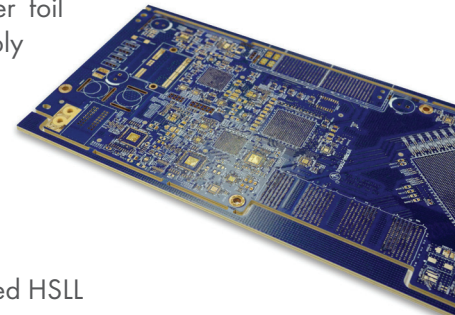
- Speeds up the Layup Process
- Improves handling of thin Copper Foils
- Suitable for Automated Handling Systems
- Can replace expensive Copper/Aluminum/Copper and Aluminum/Bonded/Copper products
- Replaces DoubleThin carrier supported foils

For example, we apply this release film to 9 µm copper foil to protect the surface and to allow for better handling during the layup process. There is no longer a need for expensive copper foil carriers.

Specifications

ACF-Screen is available in different copper foil types and thicknesses, with two types of poly release film:

- Standard copper, HTE (IPC Grade-3) for conventional FR-4 circuit boards
- High bond strength copper, for BT and Polyimide
- And Very Low Profile copper, for advanced HSLT applications
- See *reverse side* for all copper types



Copper Foil Thicknesses	
9 µm	0.25 oz
12 µm	0.375 oz
18 µm	0.5 oz
35 µm	1.0 oz
70 µm	2.0 oz

Poly Thicknesses	
High Temp. (250° C)	50 µm
	75 µm

For more info, visit our website at advancedcopperfoil.com